

# Lecture 12

Solid Surfaces. Techniques to study surfaces.

# Solid Surfaces

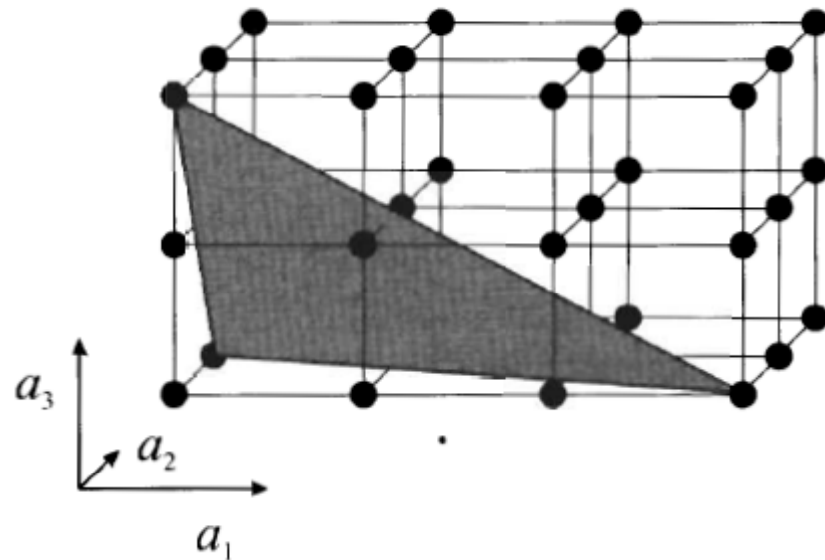
- Molecules on surfaces are not mobile (to large extent)
- Surfaces have a long-range order (crystalline)
- Shape of the surface is not entirely determined by surface tension

# Description of crystalline surfaces

- The ideal surface structure corresponding to a certain cut of bulk crystal structure is called the **substrate structure**.

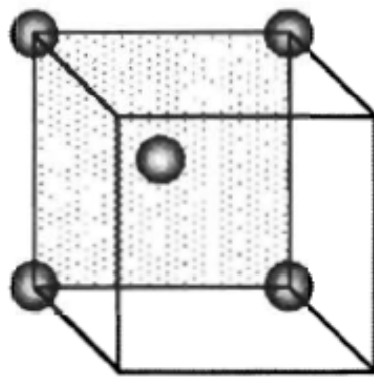
## Brief reminder from Solid State Physics

- Crystallographic orientation of a surface is determined by **Miller indices**
- How to determine Miller indices:
  - find intersection of the surface plane with the crystallographic axes in units of lattice constants
  - take the inverse
  - multiply by a common multiplier to get them all integer
  - negative numbers are represented as e.g.  $\bar{1}$
  - in hexagonal lattice 4 indices are used. The 4<sup>th</sup> one is not independent:  $(h k i l) \Rightarrow i = -(h + k)$

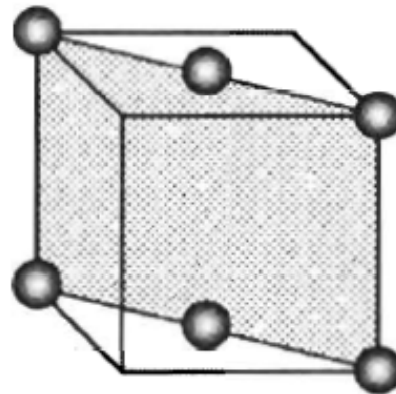


# Description of crystalline surfaces

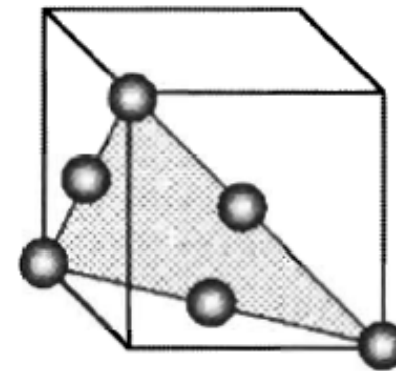
- Example: Major planes in FCC lattice



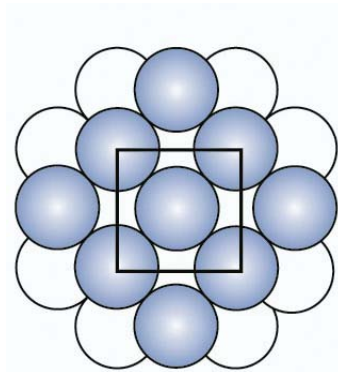
(100)



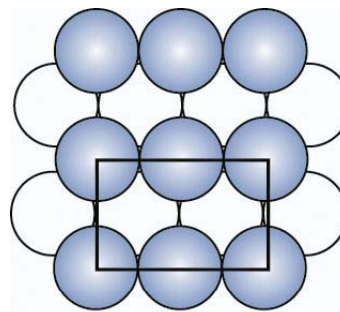
(110)



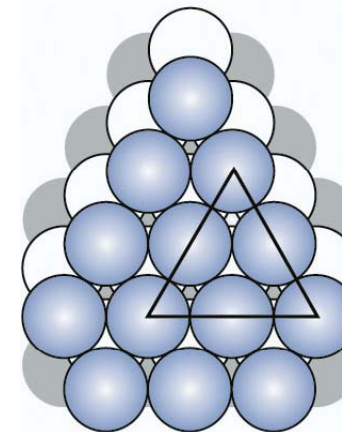
(111)



(100)



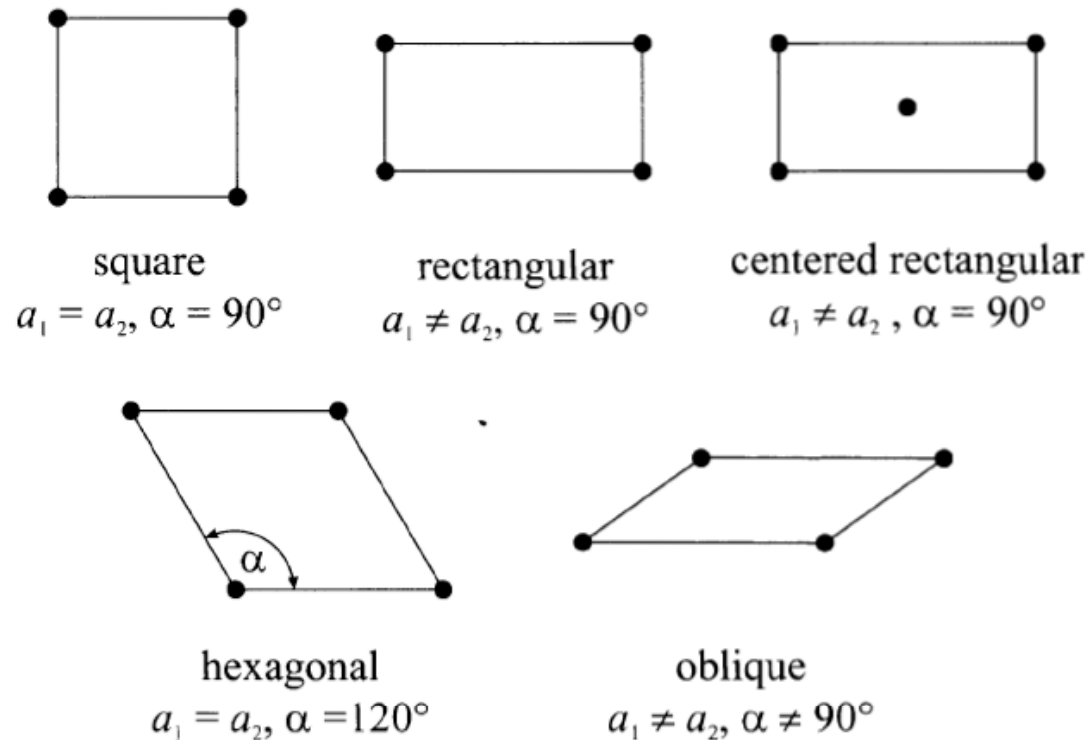
(110)



(111)

# Description of crystalline surfaces

- Crystalline surfaces can be divided into 5 Bravais lattices according to the symmetry



- Position of individual surface atoms can be indicated as:

$$\vec{r} = n \cdot \vec{a}_1 + m \cdot \vec{a}_2$$

# Surface relaxation/reconstruction

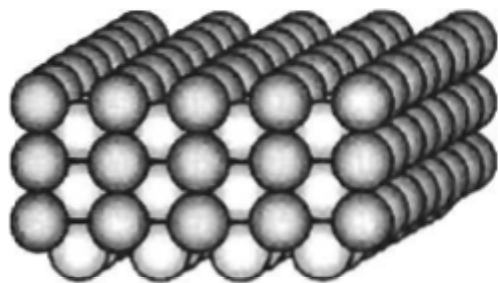
- To offset the increase in surface energy, a surface can undergo two types of changes:
  - **Surface relaxation:** distance between the topmost atomic layers is changed (usually 5-6 atomic layers), lateral distances between the atoms stay the same as in bulk.
    - usually the distance between the top two layers is reduced due to the presence of dipole layer on the surface

Example: distance reduction for (110) surfaces

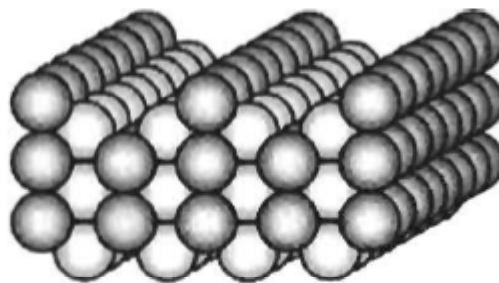
Cu	Ni	Au	Pb
0.020 Å	0.156 Å	0.125 Å	0.080 Å

# Surface relaxation/reconstruction

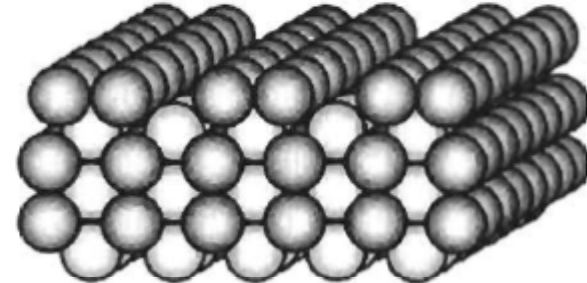
- **Surface reconstruction** – gross change in surface structure also involving changes in lateral distances
  - common for semiconductor surfaces due to the directional character of dangling bonds
  - also observed on many metals incl. Au, Ir, Pt, W



Unreconstructed  
fcc(110) surface



Missing-row (MR)  
reconstructed



Pairing row (PR)  
reconstructed

# Surface relaxation/reconstruction

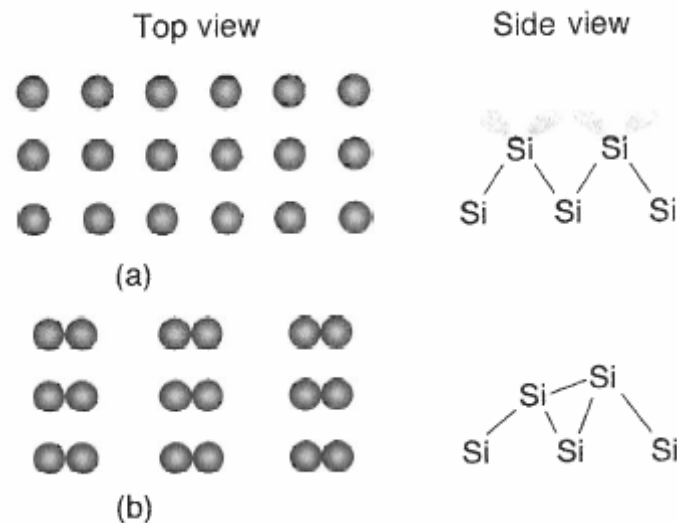
- How to describe reconstructed surfaces:

For reconstructed surface we have new unit cell vectors:

$$\vec{r} = n' \cdot \vec{b}_1 + m' \cdot \vec{b}_2$$

where:  $\vec{b}_1 = p \cdot \vec{a}_1$ ;  $\vec{b}_2 = q \cdot \vec{a}_2$

The surface structure is denoted as:  $A(hkl)(p \times q)$



Si (100)-(2x1) reconstruction



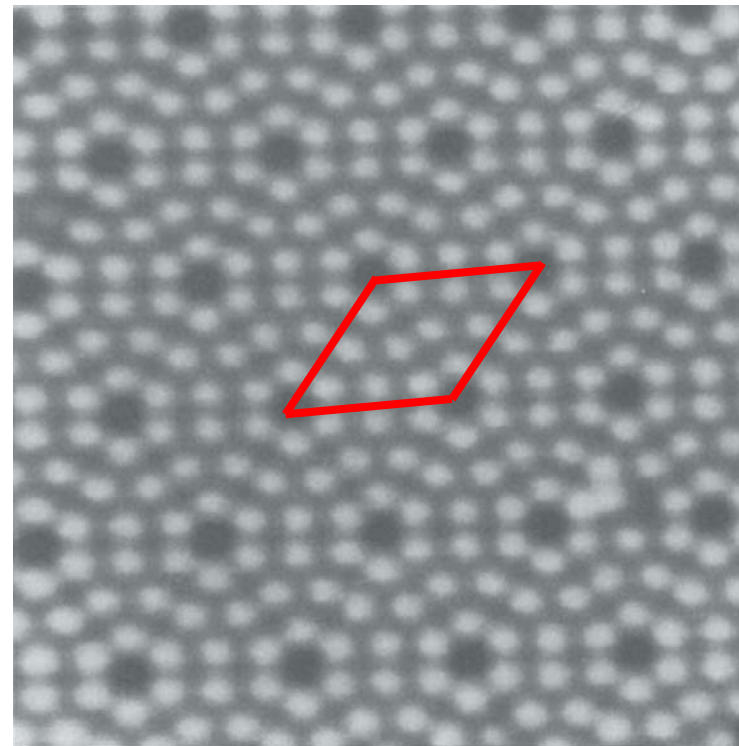
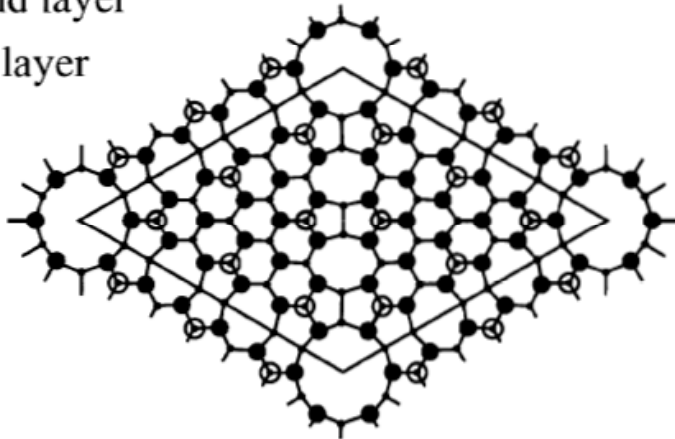
# Surface relaxation/reconstruction

- Si (111)-(7x7) reconstruction

○ top layer (adatoms)

● second layer

• third layer



# Description of the adsorbate structure

- When molecules adsorb to a crystalline surface they may form a lattice commensurate with the underlying crystalline lattice

The positions of adsorbate molecules can be written as:

$$\vec{r} = n'' \cdot \vec{c}_1 + m'' \cdot \vec{c}_2$$

and  $p' = c_1/b_1 \quad q' = c_2/b_2$

The surface structure is denoted in so-called Wood notation:

$$A(hkl)c(p' \times q')R\beta - B$$

if adsorbate unit cell  
is centered

Rotation angle

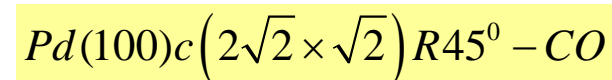
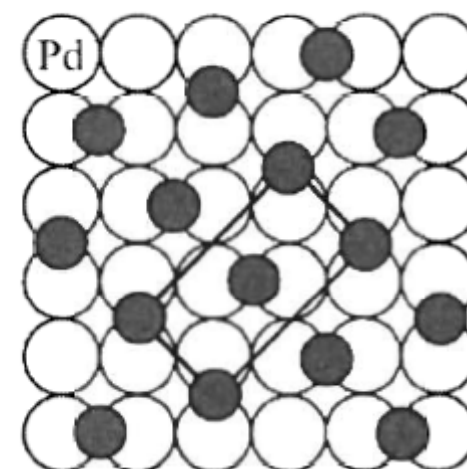
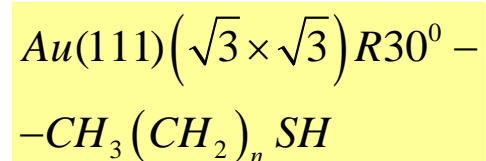
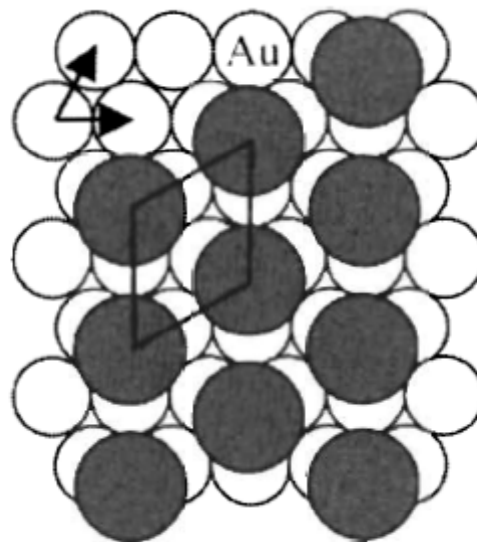
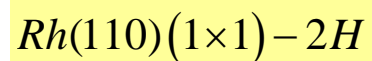
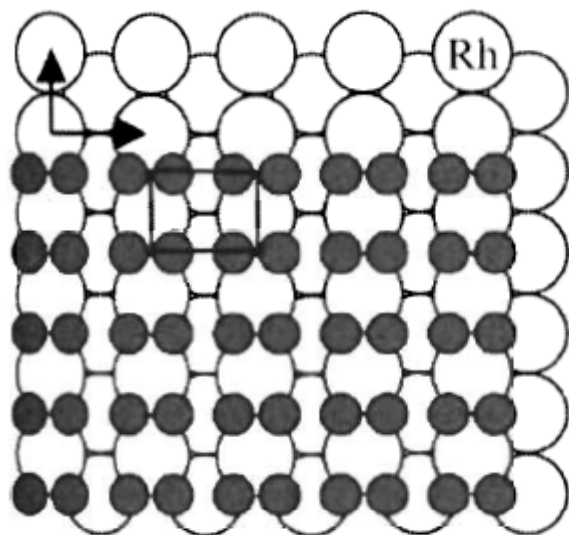
Adsorbate

Examples: Alkanethiols on gold  $Au(111)(\sqrt{3} \times \sqrt{3})R30^\circ$

# Description of the adsorbate structure

$$A(hkl)c(p' \times q')R\beta - B$$

- Examples

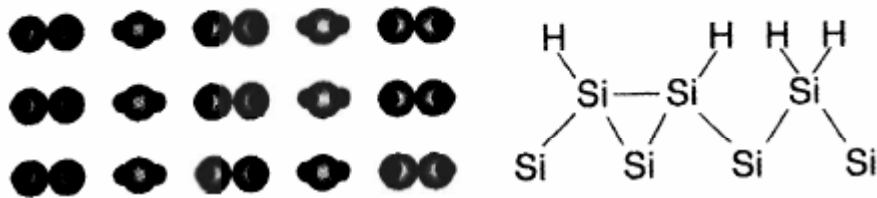


# Adsorbate induced reconstruction

- adsorbates can induce reconstruction by reacting with dangling bonds on the surface: asymmetric dimers of Si (100)-(2x1) surface are changed into symmetric Si (100)-(2x1):H, Si(111)-(7x7) is changed into Si(111)-(1x1):H and strain is relaxed



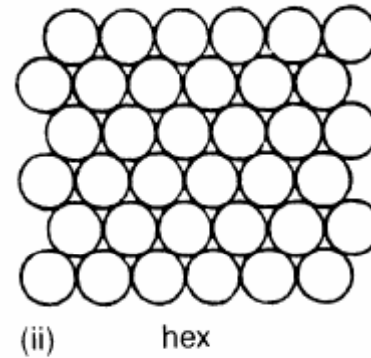
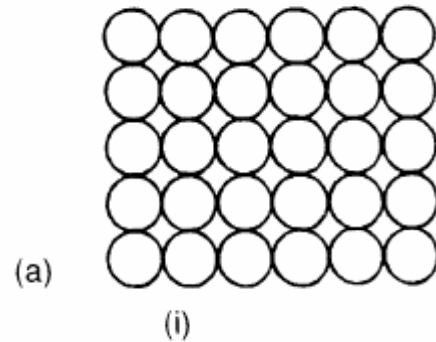
Si (100)-(2x1):H at 1ML of H



Si (100)-(3x1):H at 1.33ML of H

# Adsorbate induced reconstruction: Pt

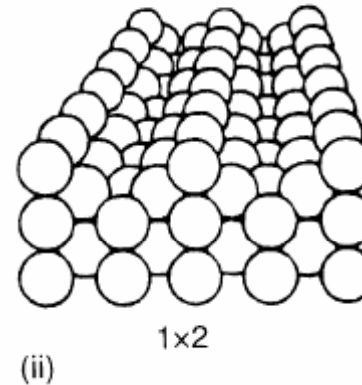
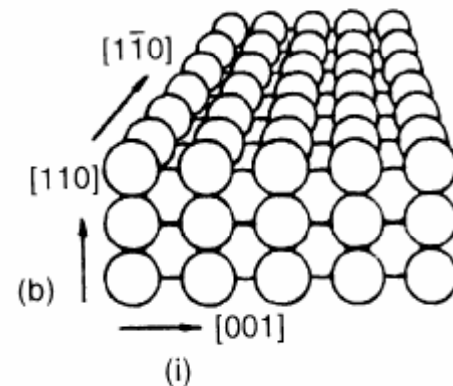
- Pt(100)-(1x1)



- Pt(100)-hex

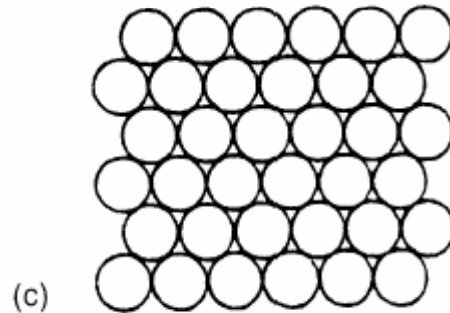
more stable, 40kJ/mol difference;  
CO adsorption:  
155kJ/mol on (1x1)  
113kJ/mol on hex

- Pt(110)-(1x1)

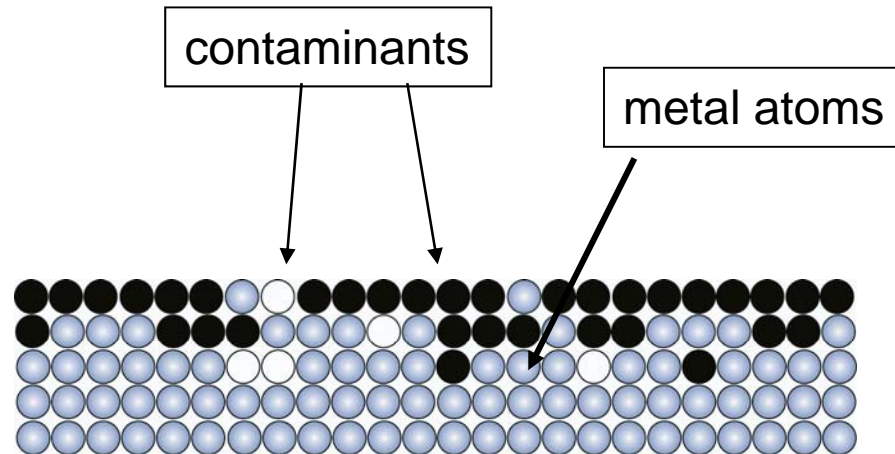


- Pt(110)-(1x2)

- Pt(111)-(1x1)



# Structure of a surface



- Surface is contaminated when exposed to the atmosphere
- Surface has it's own variety of defects

# Structure of a surface

- Flux towards the surface  $J = \frac{1}{4}n\bar{c}$ ;  $n = \frac{P}{kT}$ ;  $\bar{c} = \sqrt{\frac{8kT}{m\pi}}$
- $$J = \frac{P}{\sqrt{2\pi mkT}}, \text{ molecules/m}^2\text{s}$$

Vacuum	Pressure (Torr)	Density (molecules m <sup>-3</sup> )	Mean Free Path (m)	ML (s)
Atmospheric	760	2 x 10 <sup>25</sup>	7 x 10 <sup>-8</sup>	10 <sup>-9</sup>
Low	1	3 x 10 <sup>22</sup>	5 x 10 <sup>-5</sup>	10 <sup>-6</sup>
Medium	10 <sup>-3</sup>	3 x 10 <sup>19</sup>	5 x 10 <sup>-2</sup>	10 <sup>-3</sup>
High	10 <sup>-6</sup>	3 x 10 <sup>16</sup>	50	1
UltraHigh	10 <sup>-10</sup>	3 x 10 <sup>12</sup>	5 x 10 <sup>5</sup>	10 <sup>4</sup>

# Preparation of clean surfaces

- Usually proper surfaces are cut from a single crystal (orientation controlled by X-ray),
- hard materials are grounded and polished
- soft materials are chemically/electrochemically cleaned
- additional cleaning in UHV chamber
  - thermal treatment (annealing of defects, desorption of adsorbates)
  - cleavage
  - sputtering (surface layer removed by ion bombardement)
- In-situ preparation: evaporation, molecular beam epitaxy (MBE), sputtering



# Thermodynamics of solid surfaces

- Surface strain:

$$d\varepsilon_{tot} = \frac{dA}{A} = d\varepsilon_p + d\varepsilon_e$$

increase of area per molecule

insertion of extra molecules, area per molecule constant

$$dW = \gamma^s dA = d(E_s N) = E_s \frac{\partial N}{\partial A} dA + N \frac{\partial E_s}{\partial A} dA$$

- for plastic deformation:

$$\left( \frac{\partial E_s}{\partial A} \right)_{pla} = \left( \frac{\partial E_s}{\partial (N \sigma_A)} \right) = \frac{1}{\sigma_A} \left( \frac{\partial E_s}{\partial (N)} \right) = 0$$

$$\gamma_{pla}^s = \left( E_s \frac{\partial N}{\partial A} \right)_{pla} = \frac{E_s}{\sigma_A} \equiv \gamma$$

# Thermodynamics of solid surfaces

- Elastic deformation

$$\left( \frac{\partial E_s}{\partial A} \right)_{pla} = \left( \frac{\partial E_s}{\partial (N \sigma_A)} \right) = \frac{1}{\sigma_A} \left( \frac{\partial E_s}{\partial (N)} \right) = 0$$

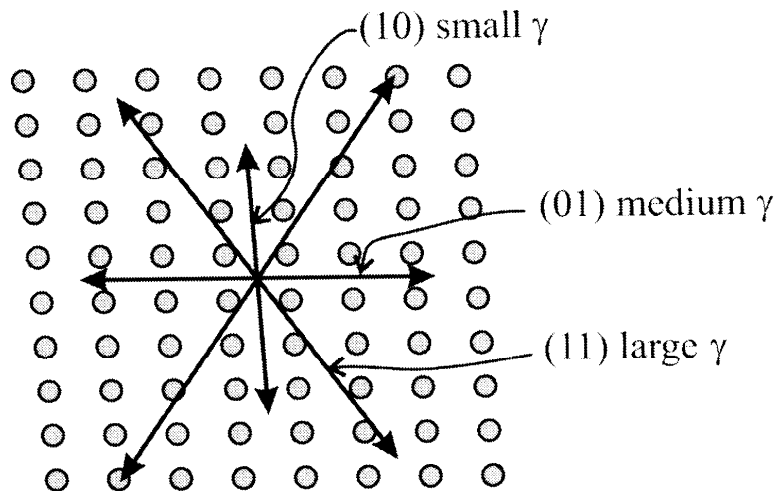
$$\gamma^s_{ela} = \left( N \frac{\partial E_s}{\partial A} \right)_{ela} = \frac{\partial E_s}{\partial \sigma_A} = \gamma + \sigma_A \left. \frac{\partial \gamma}{\partial \sigma_A} \right|$$

$$\gamma^s_{ela} \equiv \Upsilon = \gamma + \left. \frac{\partial \gamma}{\partial \varepsilon_e} \right|$$

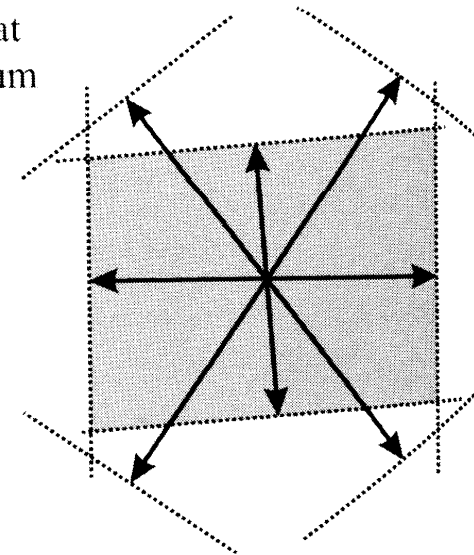
↖  
Surface stress

# Shape of a crystal

- How to plot the shape of the crystal:



Shape at equilibrium



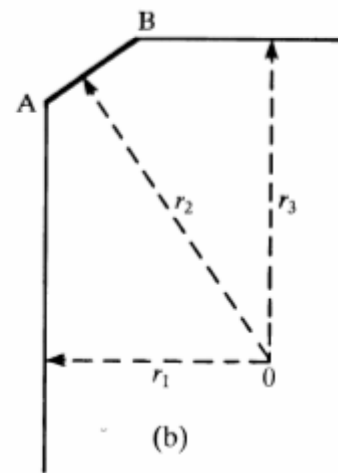
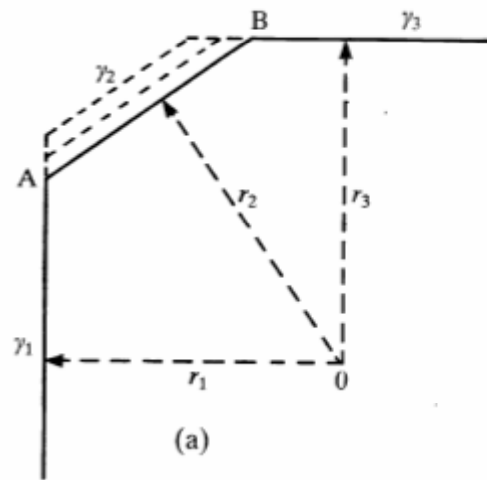
vectors proportional  
to surface tension of  
the corresponding  
plane

# Shape of a crystal

- Crystal faces grow in such a way as to minimize the total surface energy
- Wulff's law:

$$\frac{\gamma_1}{r_1} = \frac{\gamma_2}{r_2} = \frac{\gamma_3}{r_3} = \text{const}$$

Adsorption of impurities might steer the crystal away from the equilibrium shape



# Shape of a crystal

- Example: growth of a prismatic crystal at constant volume

$$dF = -SdT - pdV + \mu dn + \gamma dA$$

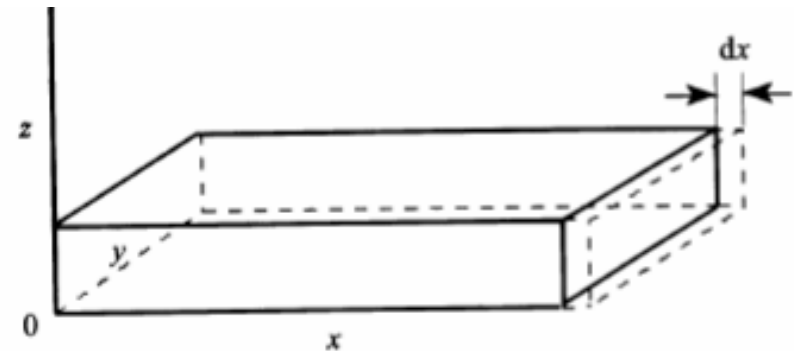
$$dT = 0; dV_s = -dV_{liq}; dn_s = -dn_{liq}; \mu_s = \mu_{liq}$$

$$dF_s - dF_{liq} = 0 = -(p_s - p_{liq})dV + \sum_i \gamma_i dA_i$$

$$-(p_s - p_{liq})yzdx + 2\gamma_y zdx + 2\gamma_z ydx = 0$$

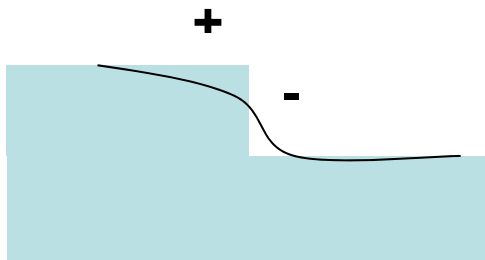
$$\frac{\gamma_y}{y} + \frac{\gamma_z}{z} = \frac{1}{2}(p_s - p_{liq}) = \frac{\gamma_y}{y} + \frac{\gamma_x}{x} = \frac{\gamma_x}{x} + \frac{\gamma_z}{z}$$

$$\frac{\gamma_x}{x} = \frac{\gamma_y}{y} = \frac{\gamma_z}{z} = \text{const} = \frac{1}{4}(p_s - p_{liq}) \quad \text{compare: } -\Delta p = \gamma \left( \frac{1}{R_1} + \frac{1}{R_2} \right)$$

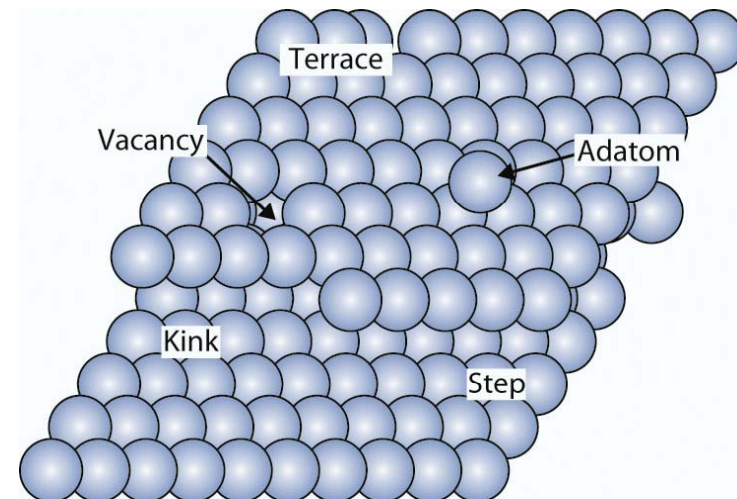


# Vicinal surfaces

- vicinal surface – high index plane (hkl) with  $h, k, l > 1$ )
- have tendency to stay close to low-index structure by introducing steps or facets
- electronic structure (and reactivity) of steps is different from terraces!
- bimetallic surfaces: as the energy of A-A, B-B, and A-B bonds can be different, the surface will be enriched by low surface energy species



Smoluchowski smoothing



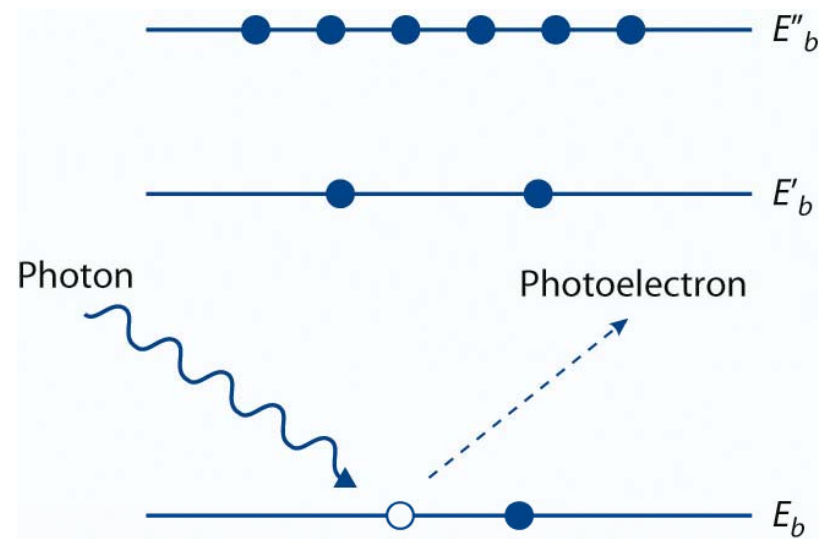
# Techniques for studying solid surface

- Spectroscopic methods give information on identity and chemistry of the surface
- X-ray photoelectron spectroscopy (XPS)
- developed in 1950s by Kai Siegbahn (Nobel price 1981)
- provides information on binding energy

$$E_k = h\nu - E_b + \phi$$

kinetic energy of  
a photoelectron

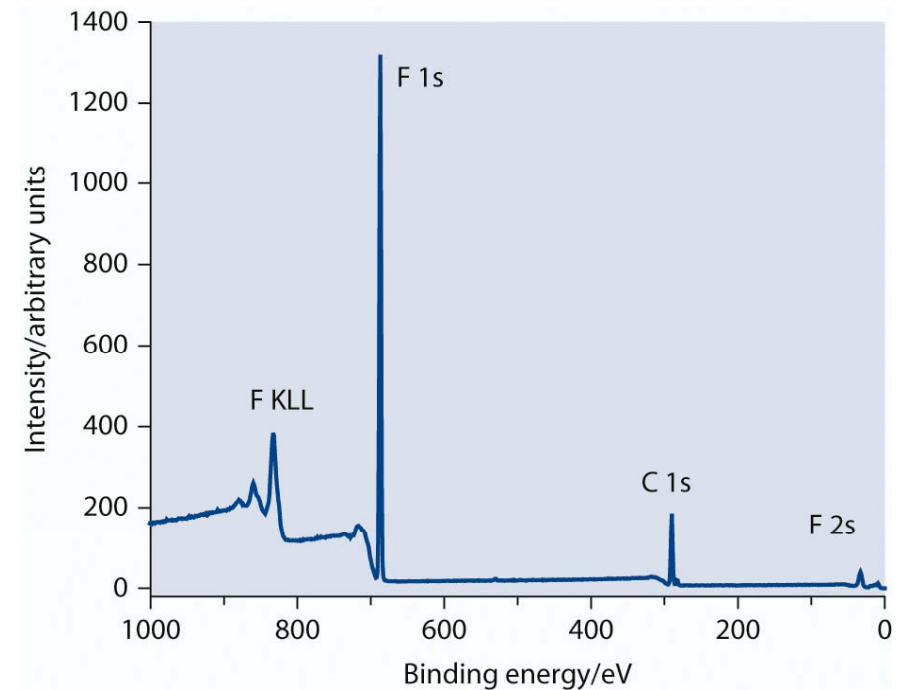
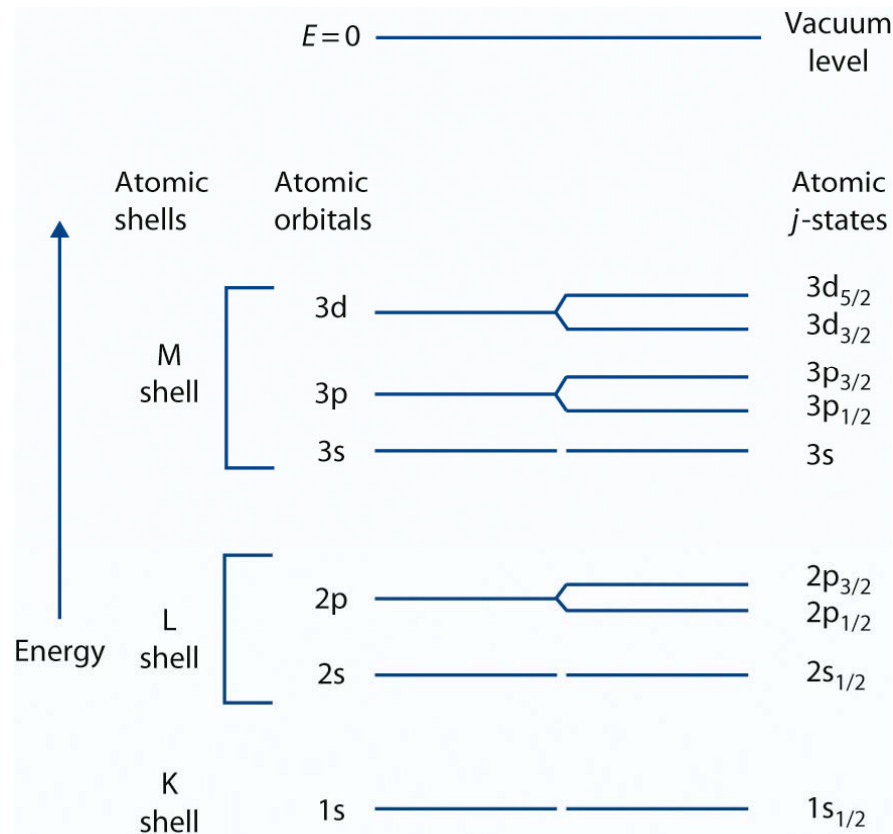
spectrometer  
work function



# Spectroscopic and diffraction methods

- XPS

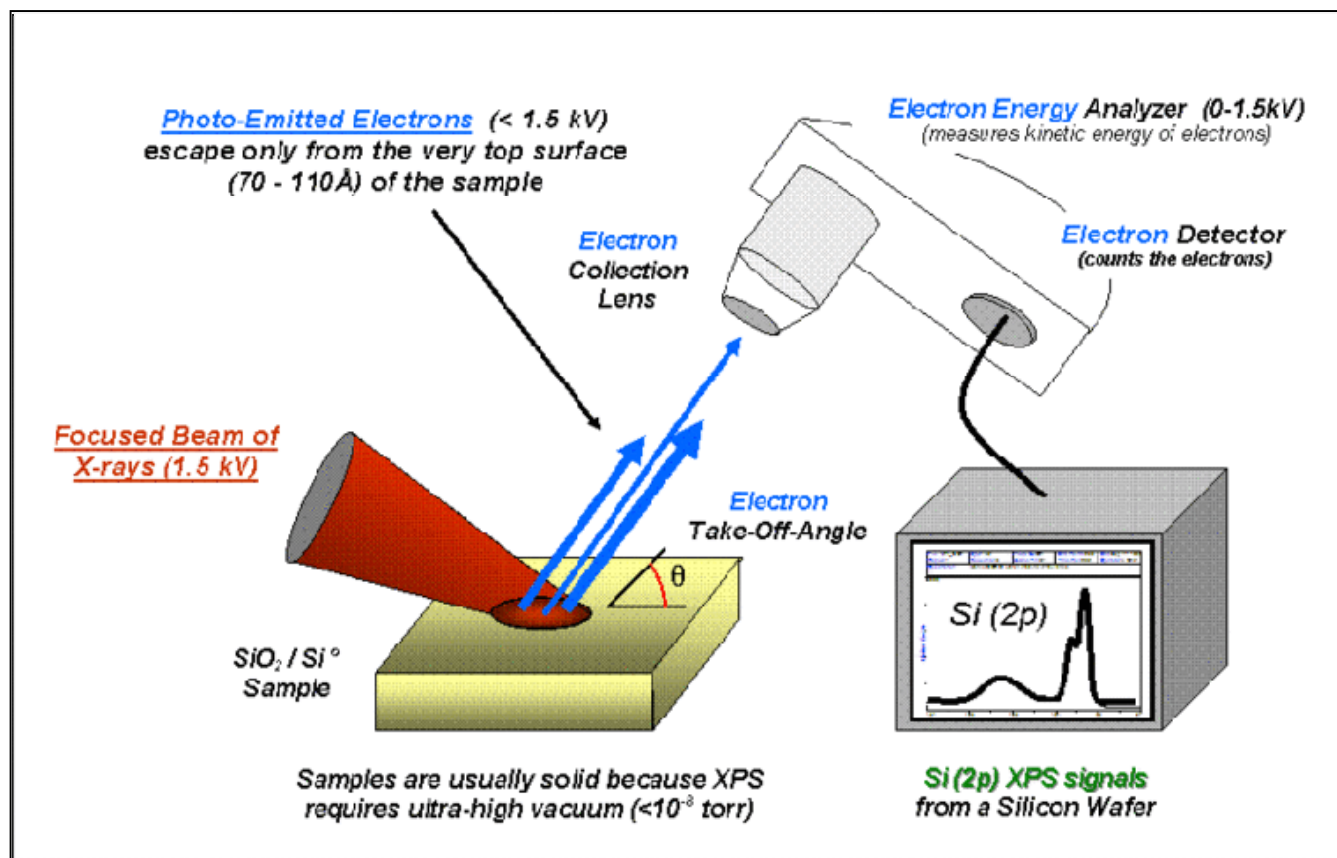
$$E_k = h\nu - E_b + \phi$$



XPS spectrum of FEP  
(fluorinated ethylene propylene)



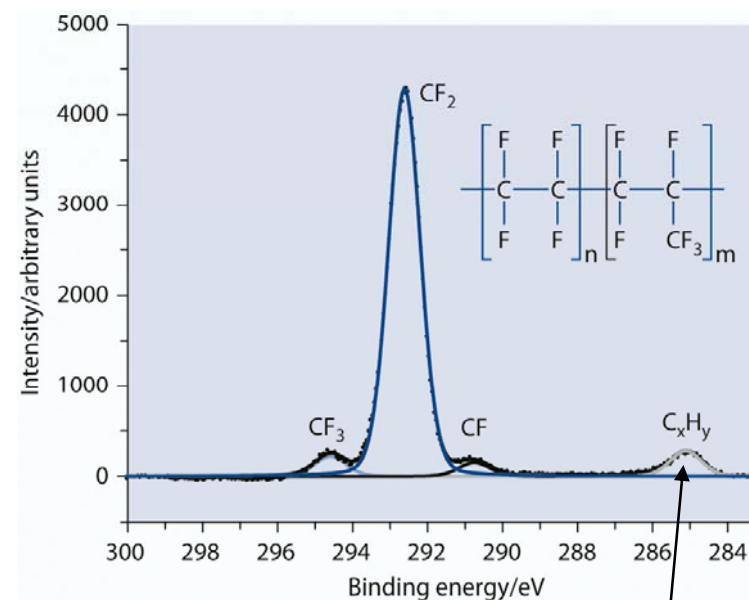
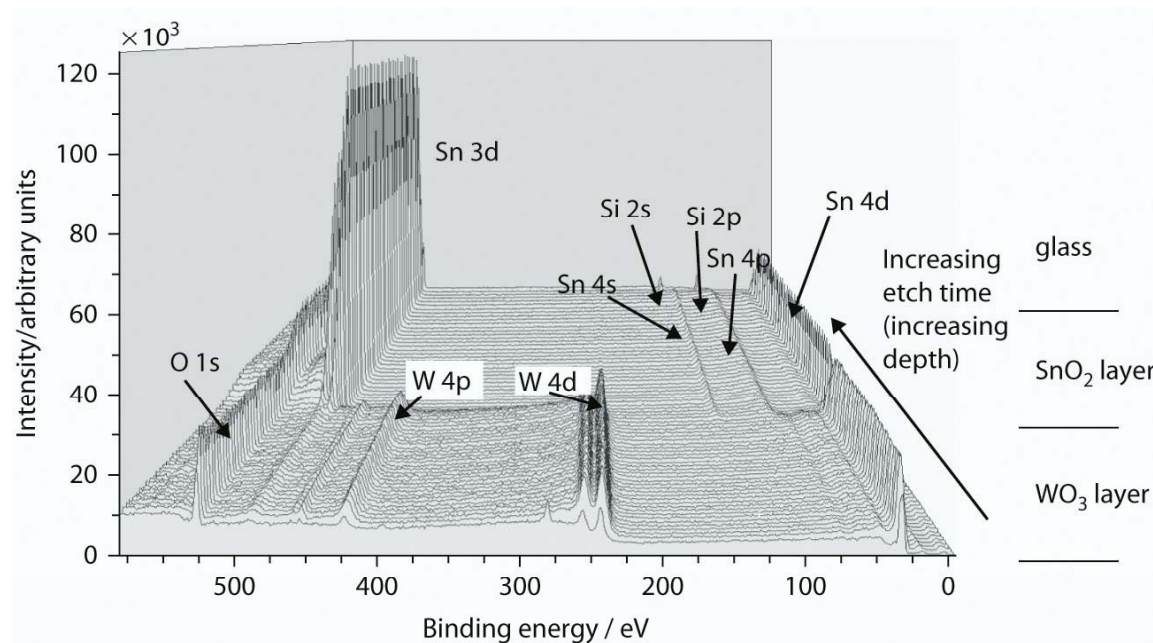
# XPS



- XPS is also known as ESCA, an abbreviation for Electron Spectroscopy for Chemical Analysis.
- XPS detects all elements with an atomic number (Z) between those of lithium (Z=3) and lawrencium (Z=103). This limitation means that it cannot detect hydrogen (Z=1) or helium (Z=2).
- Detection limits for most of the elements are in the parts-per-thousand (PPT<sub>h</sub>) range.
- XPS is routinely used to analyze inorganic compounds, metal alloys, semiconductors, etc.

# XPS

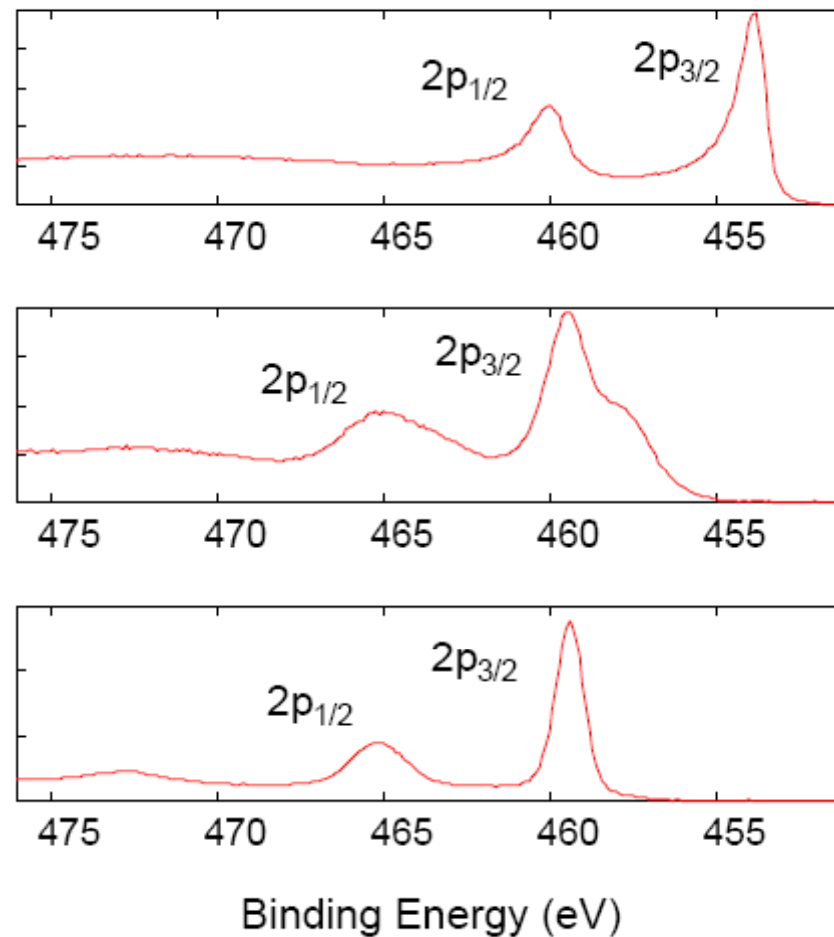
- depth profiling is possible (w. ion gun)
- can be measured with high spatial resolution
- **peak position** depends on chemical environment (**chemical shift**)
- **peak intensity** depends on the concentration (and photoemission cross-section)



carbon surface contamination

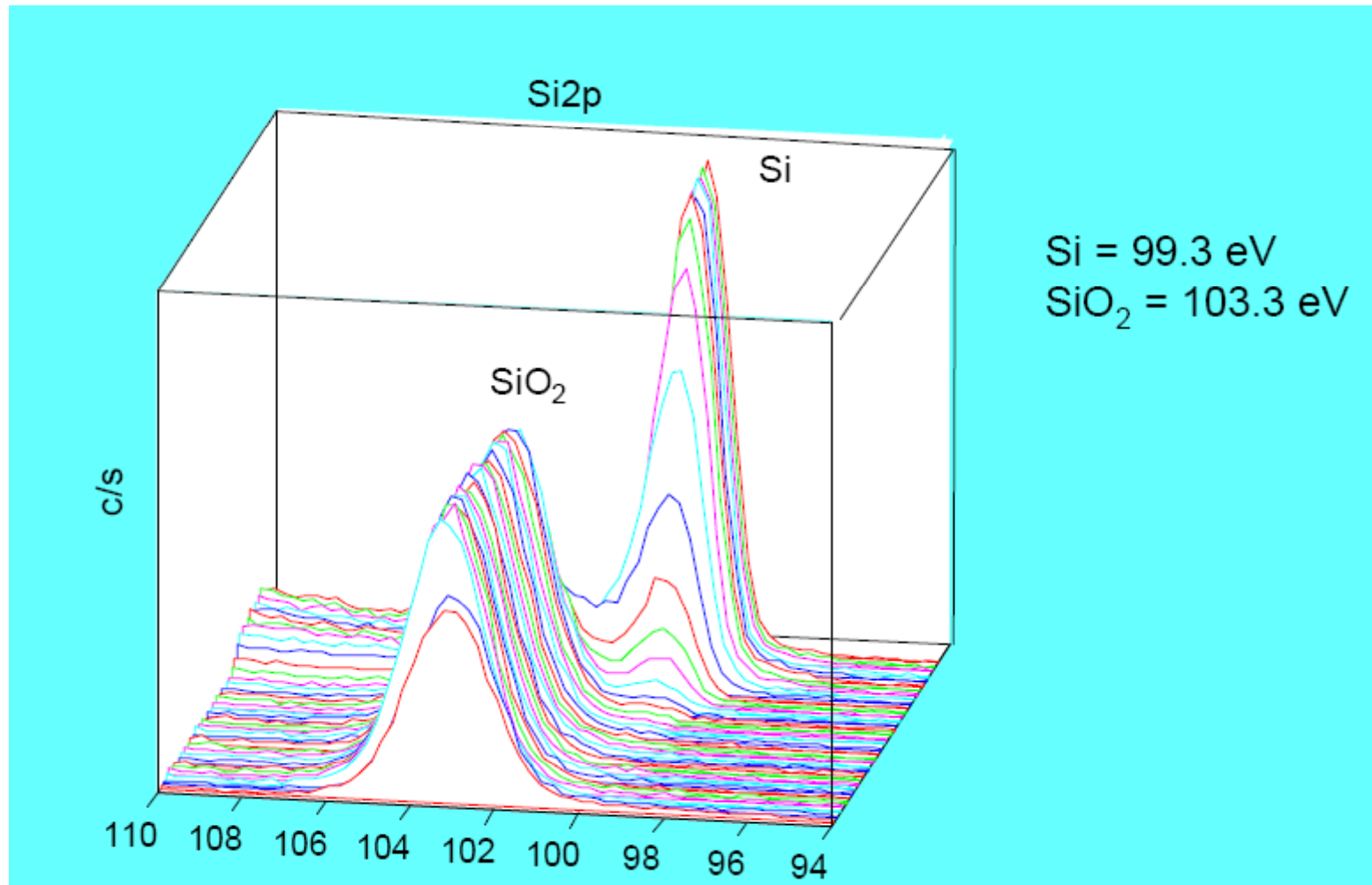
# XPS

- Chemical shift: Ti – TiO<sub>2</sub>.



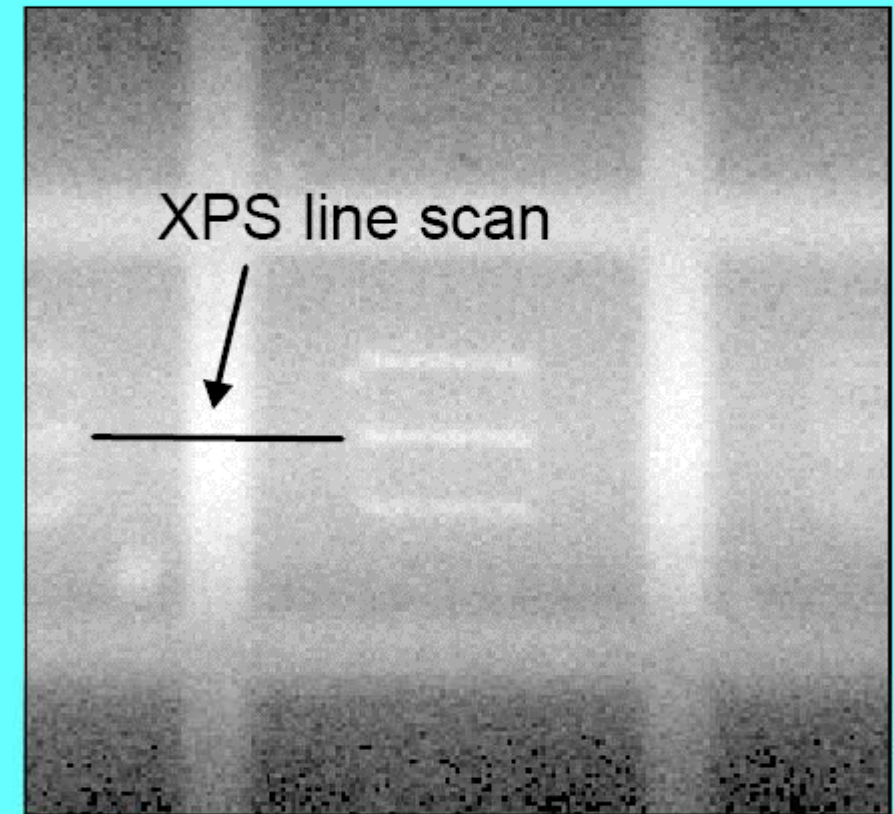
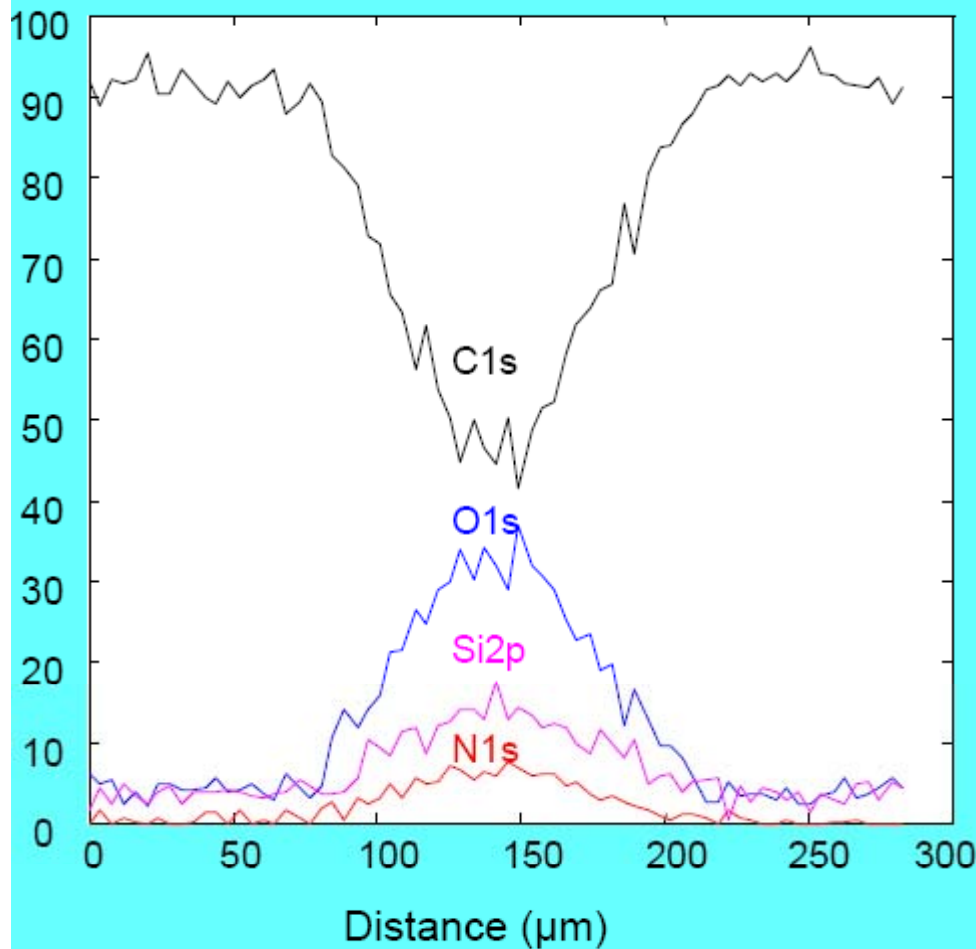
# XPS

- Depth profiling of a chemical shift in Si/SiO<sub>2</sub>.



# XPS

- Imaging and line profiling: profiling a polymer film with 20 $\mu\text{m}$  Al  $K_{\alpha}$  X-ray beam

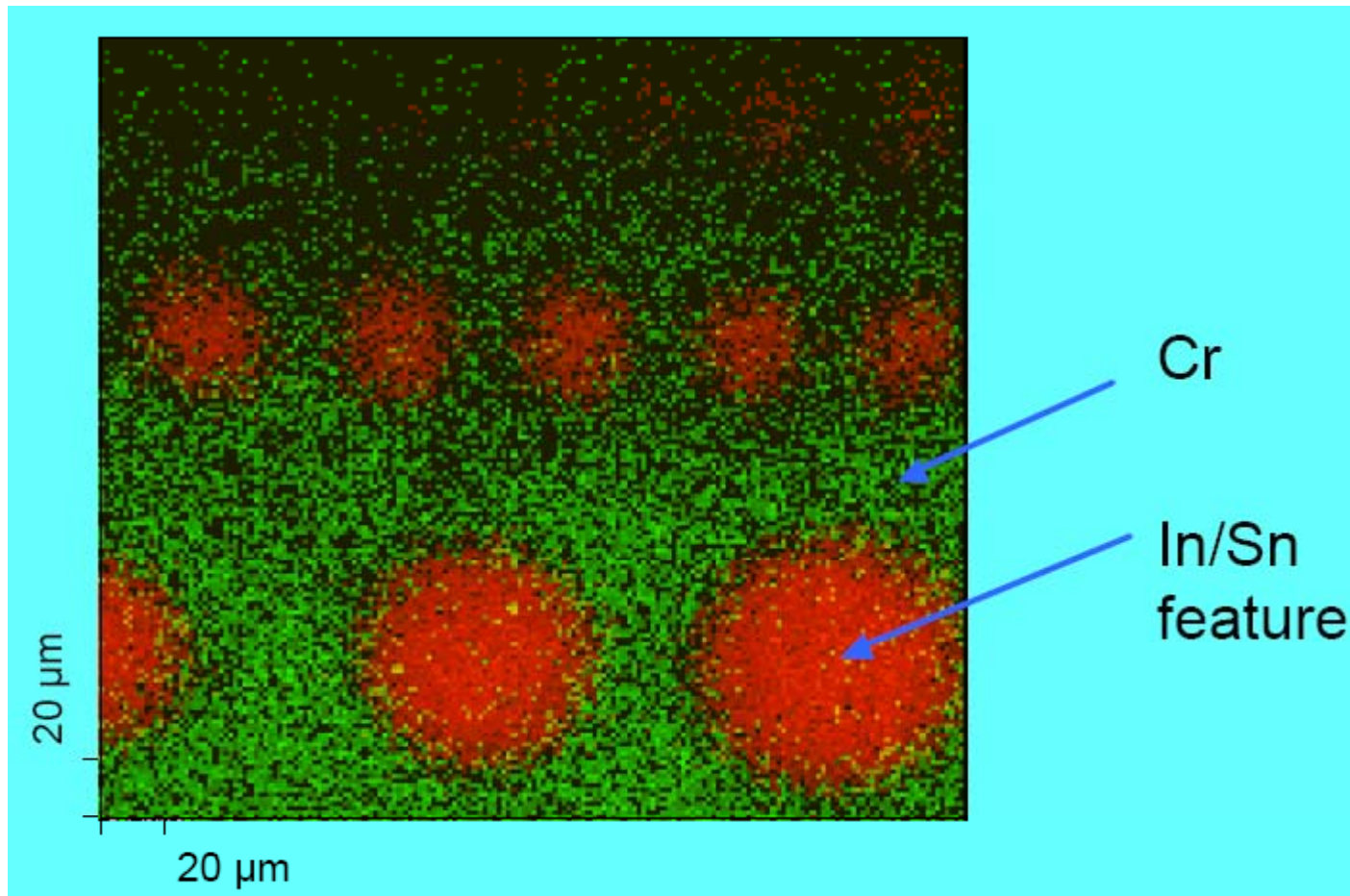


100  $\mu\text{m}$

Secondary x-ray image

# XPS

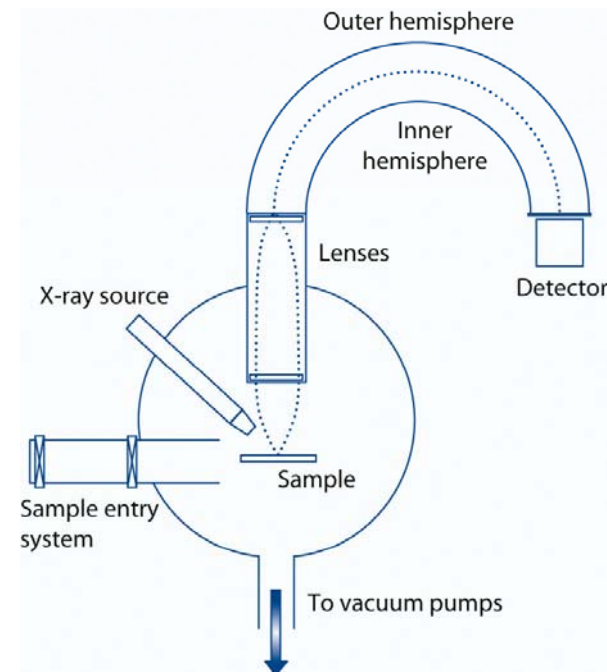
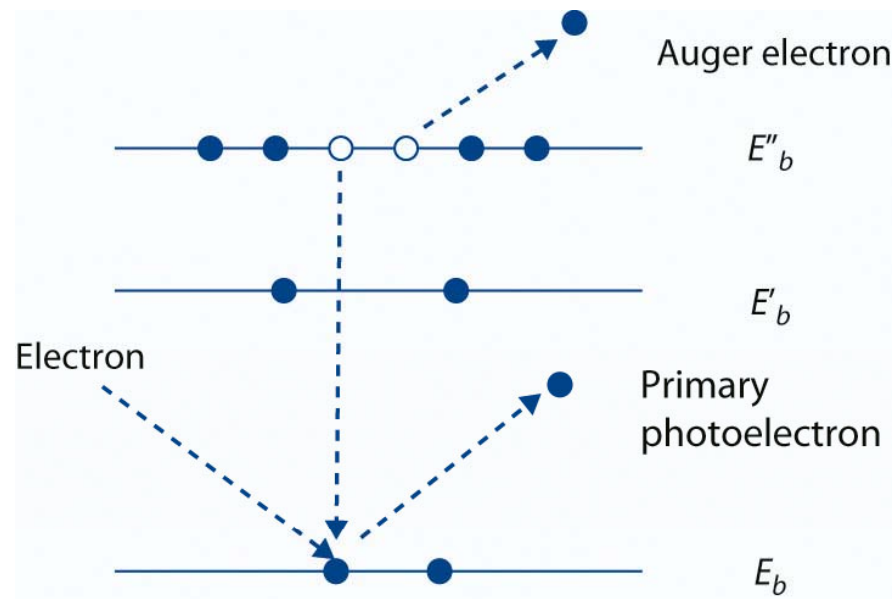
- XPS elemental map





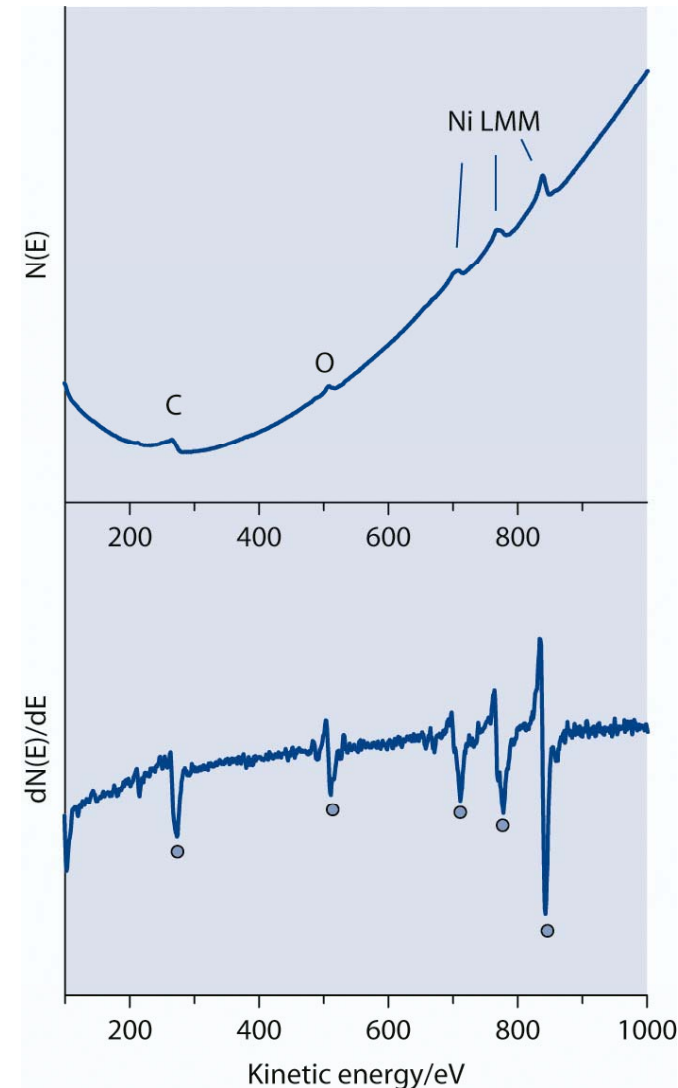
# Auger electron spectroscopy

- Auger process:
  1. incident photon (electron) causes ejection of a primary photoelectron
  2. excited ion relaxes either by X-ray fluorescence or by Auger process (ejection of an Auger electron)



# Auger spectroscopy

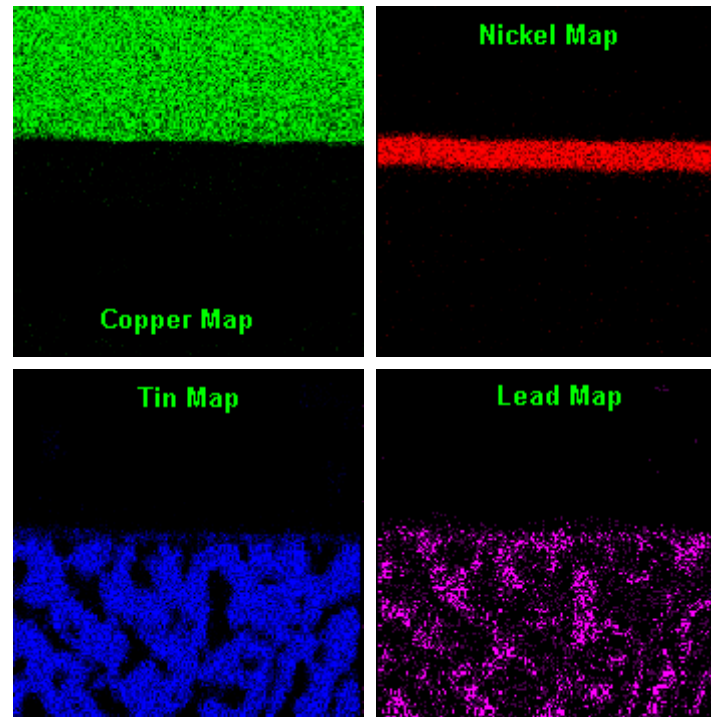
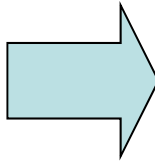
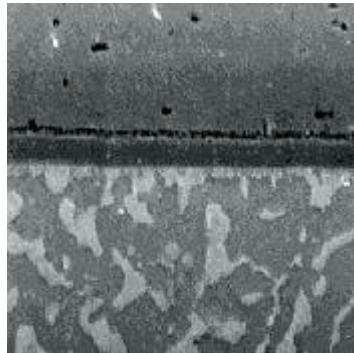
- in Auger spectroscopy position of peaks is determined by binding energy, doesn't depend on the incident energy
- peaks are marked as e.g.  $KL_2L_3$  where:
  - first letter: initial ionization shell;
  - second: shell where electron dropped from:
  - third: shell where electron is ejected from





# Energy Dispersive X-ray Analysis (EDX)

- Not really a surface technique (generated from up to 10um in depth)



# Secondary ion mass spectroscopy (SIMS)

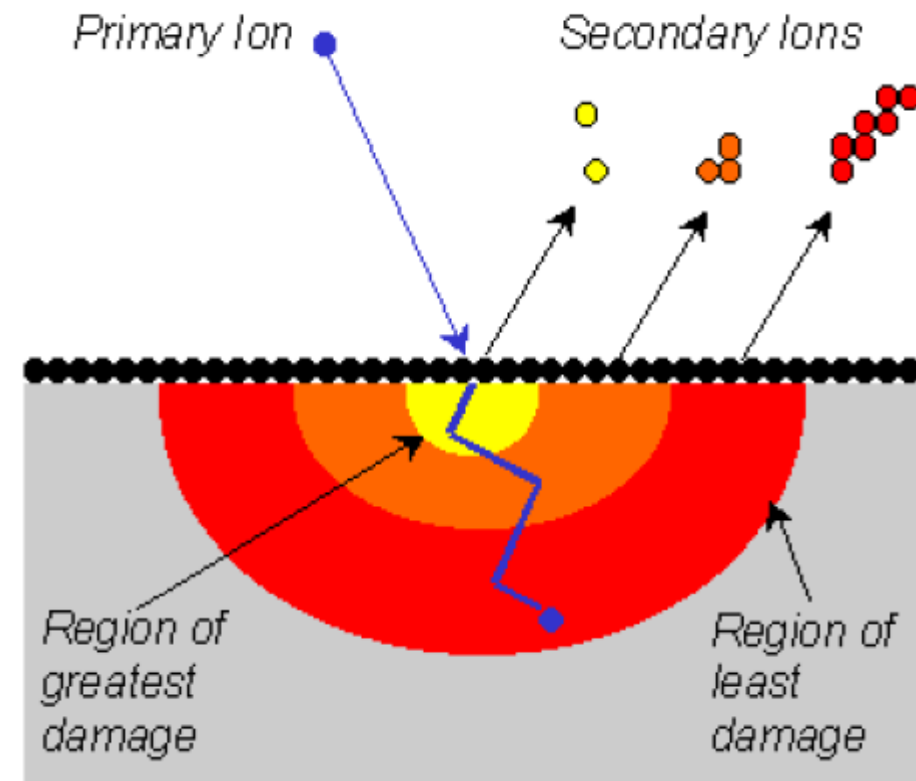
- surface is bombarded by ions of high energy, removed ions analyzed for their masses

## Advantages:

- excellent sensitivity for various surfaces incl. organic films, polymers, semiconductors etc.
- can detect all elements and isotopes including H;
- depth profile possible

## Weaknesses:

- Destructive
- No chemical information

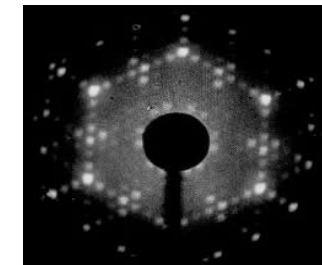
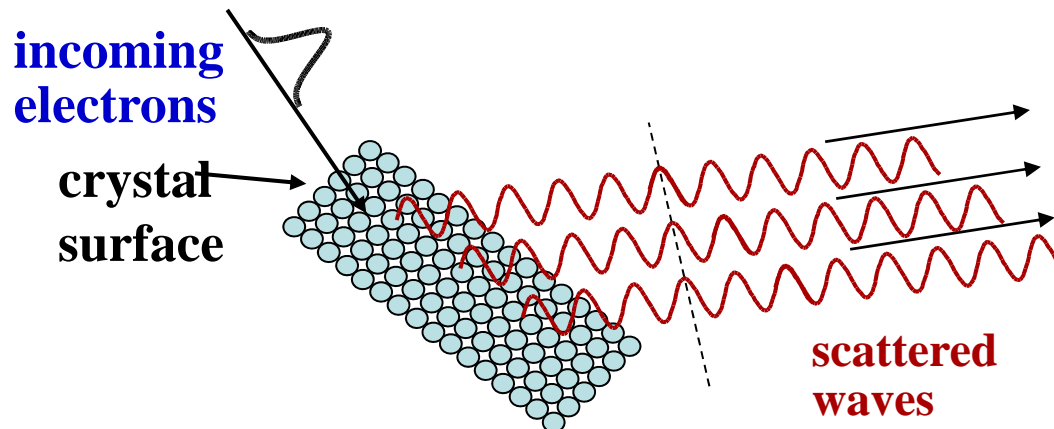
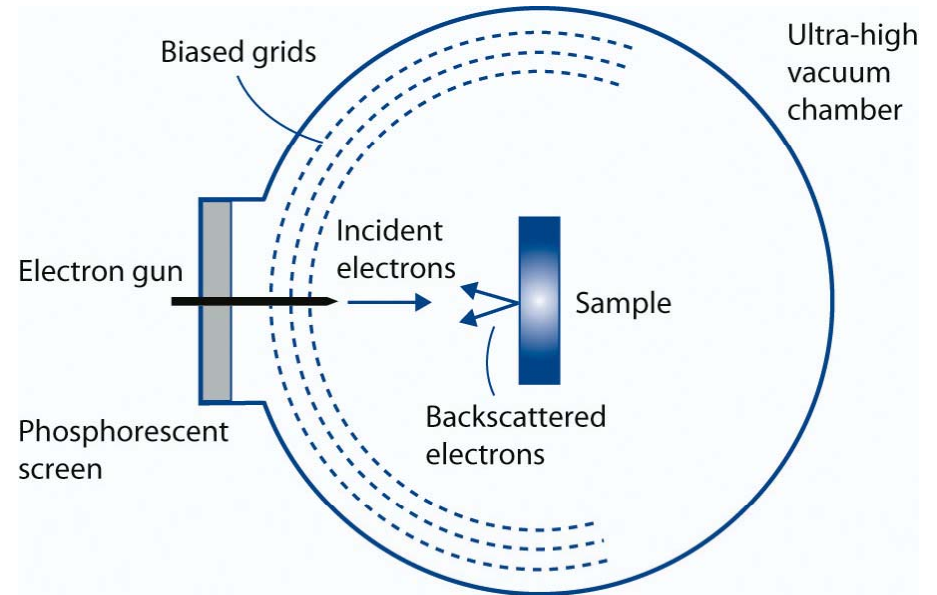


# Diffraction-based techniques

- Low-energy electron diffraction LEED
- Grazing incidence X-ray diffraction GIXD
- Atomic beam diffraction

# Low energy electron diffraction (LEED)

- electrons of low energy (20eV-1keV) are elastically scattered from sample)
- due to low penetration depth (0.5-1.5nm) information about few top layers is obtained
- produces information on crystal structure of surface layer and the coordinates of atom within the unit cell
- usually other measurements (or assumptions) are required as multiple scattering complicates the situation



**LEED diffraction pattern**

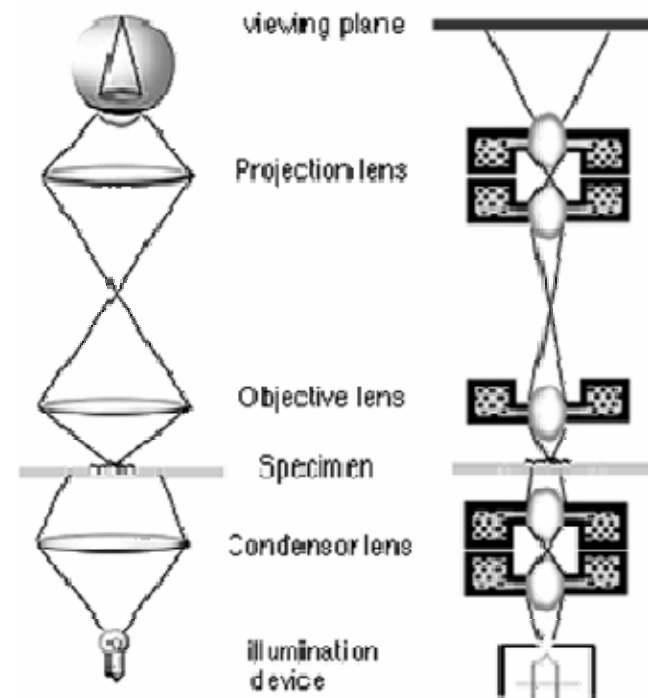
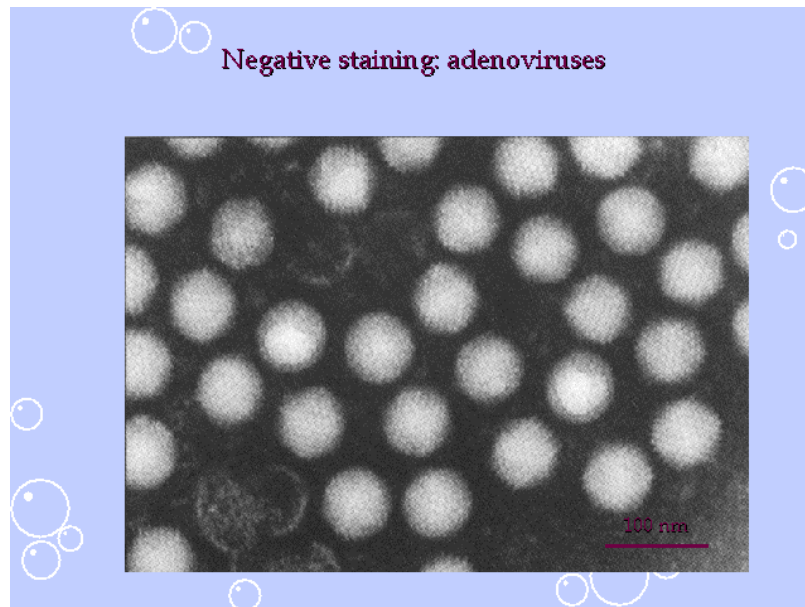
# Imaging techniques

- Scanning Electron Microscopy (SEM)
- Transmission Electron microscopy (TEM)
- Scanning Probe Microscopy (STM, AFM etc.)

# TEM

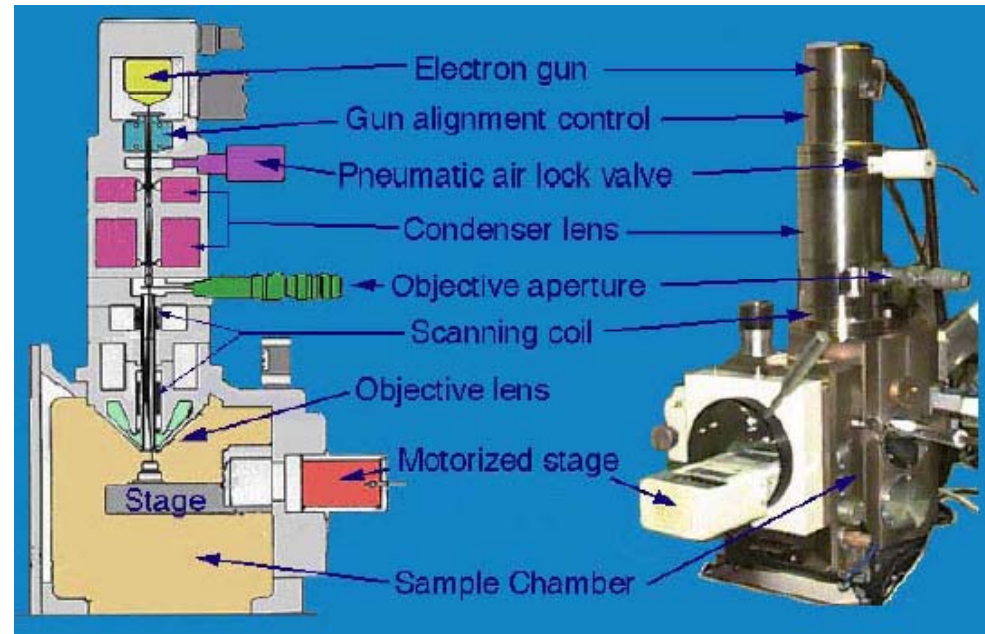
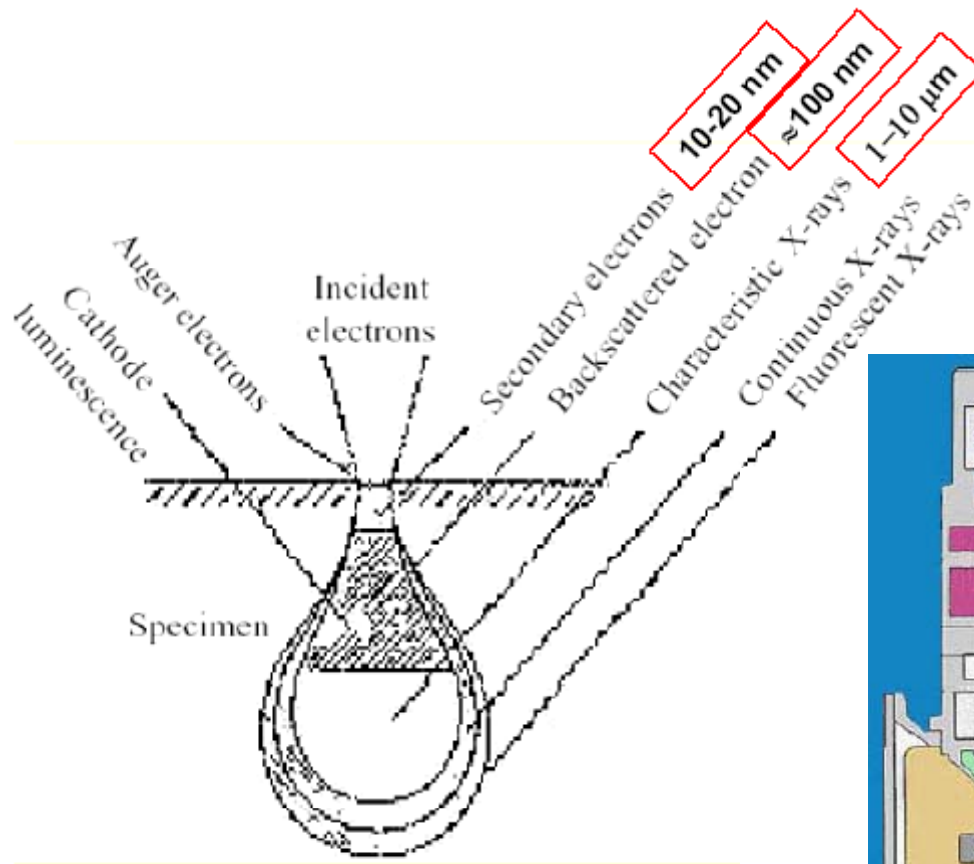
- Imaging electrons transmitted through thin (100nm and below) sections of a sample
- typical energies 1-400 keV
- wavelength: 0.4-0.02 Å

$$\lambda = h / p = h / \sqrt{2mE}$$



# SEM

- Backscattered electron imaging
- Secondary electron imaging
- EDX

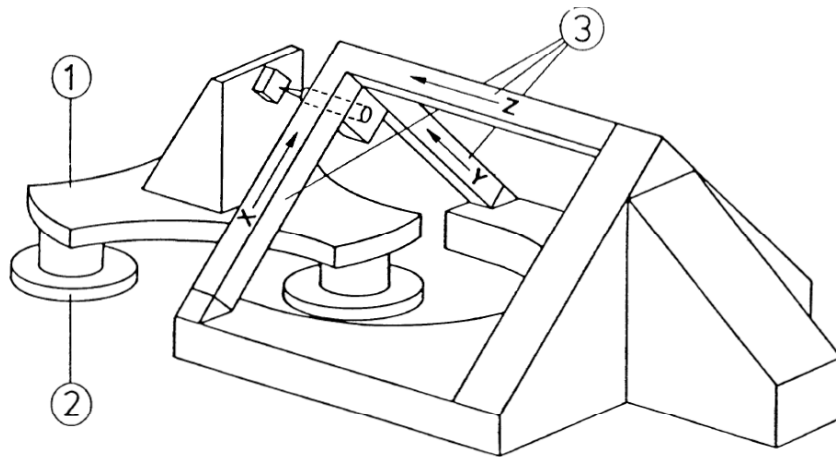




# Scanning probe techniques

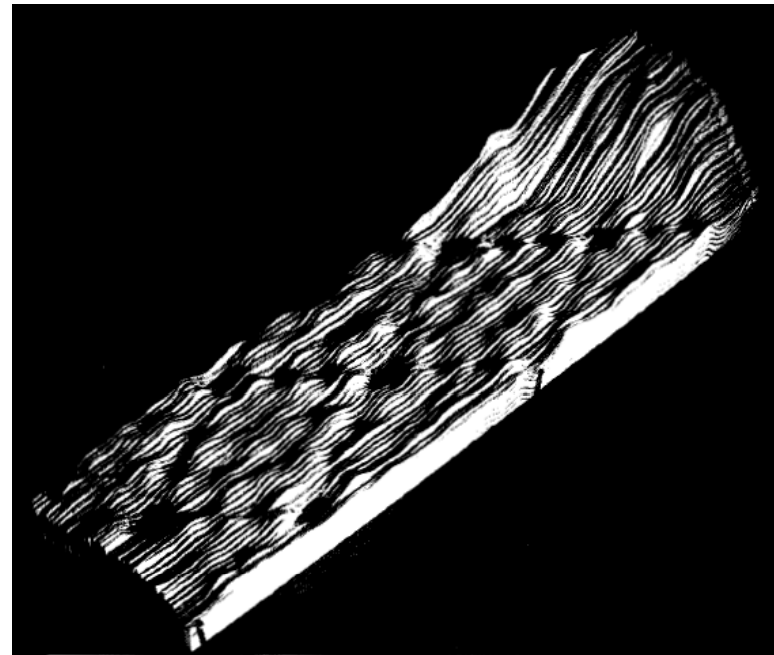
- Binning and Rohrer 1982 (Nobel prize 1985)

Binning and Rohrer, Helv.Phys.Acta 55, 726 (1982)



## **Provides:**

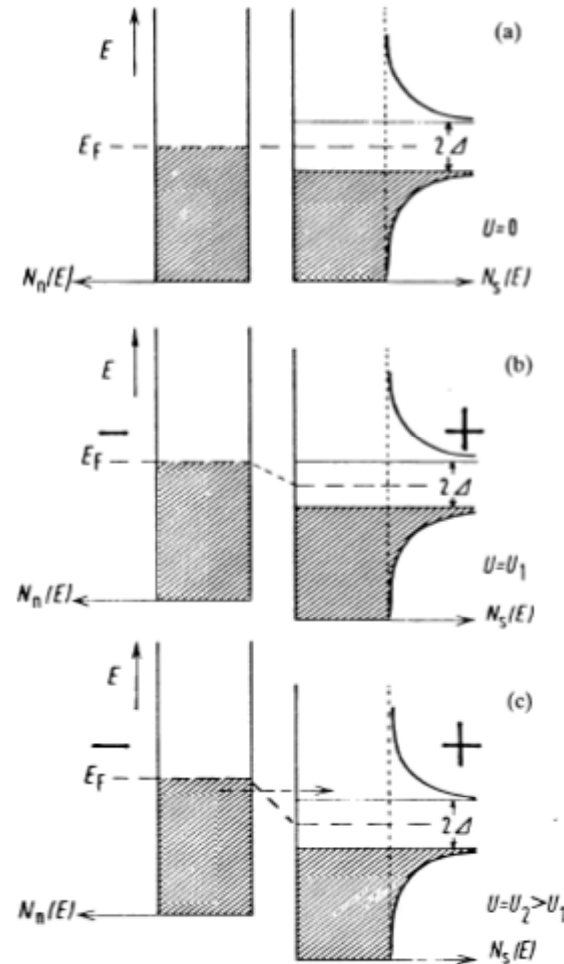
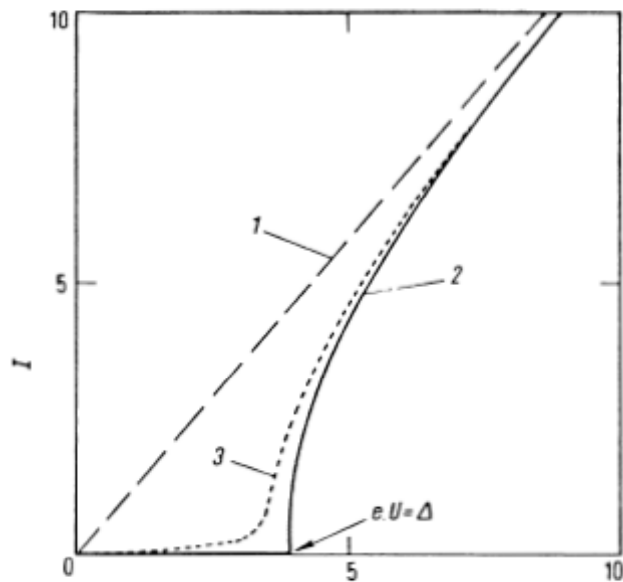
- topographical information (electron density vs. coordinate)
- spectroscopic information: electron density of states vs. energy)





# Tunneling

- Tunneling and band structure:
  - Metal-Superconductor



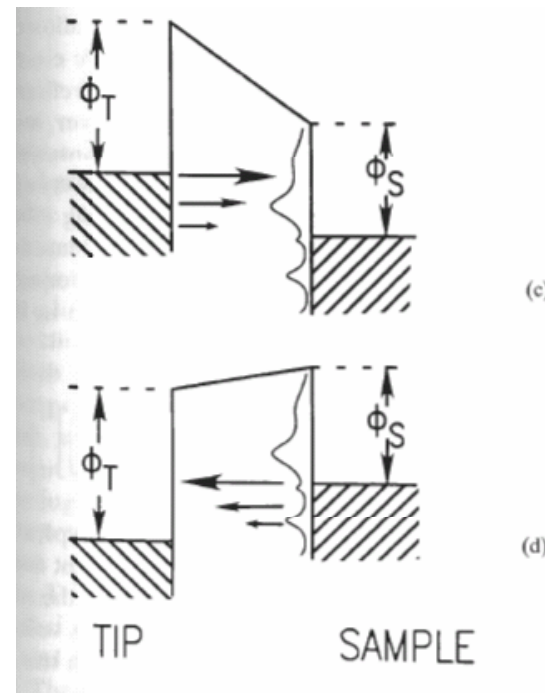
# STM spectroscopy

- In constant current STM we are imaging LDOS at fixed energy  $E_F + eV$
- If we scan a tip/sample voltage at a point we will profile LDOS vs  $E_F + eV$  at a given point

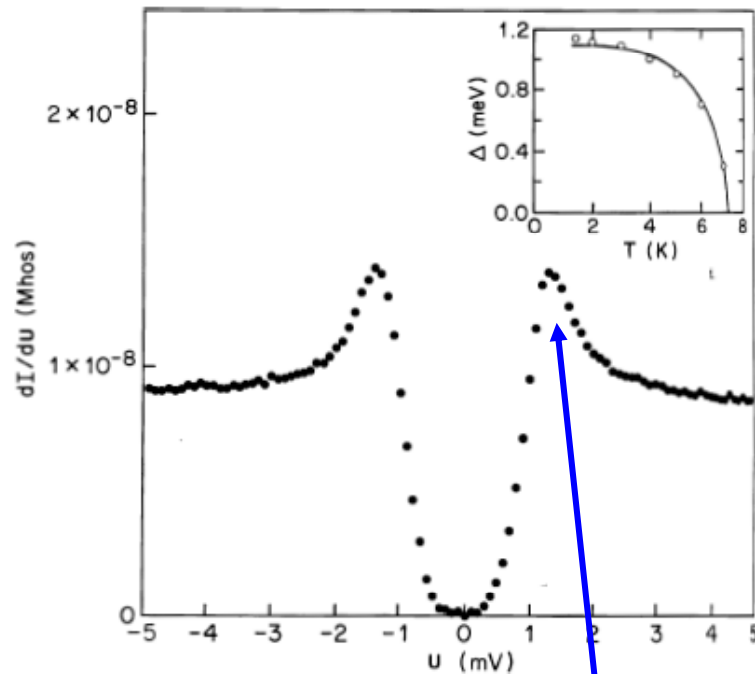
$dI/dV \sim$  density of states

Positive bias applied,  
electrons tunnel from the tip

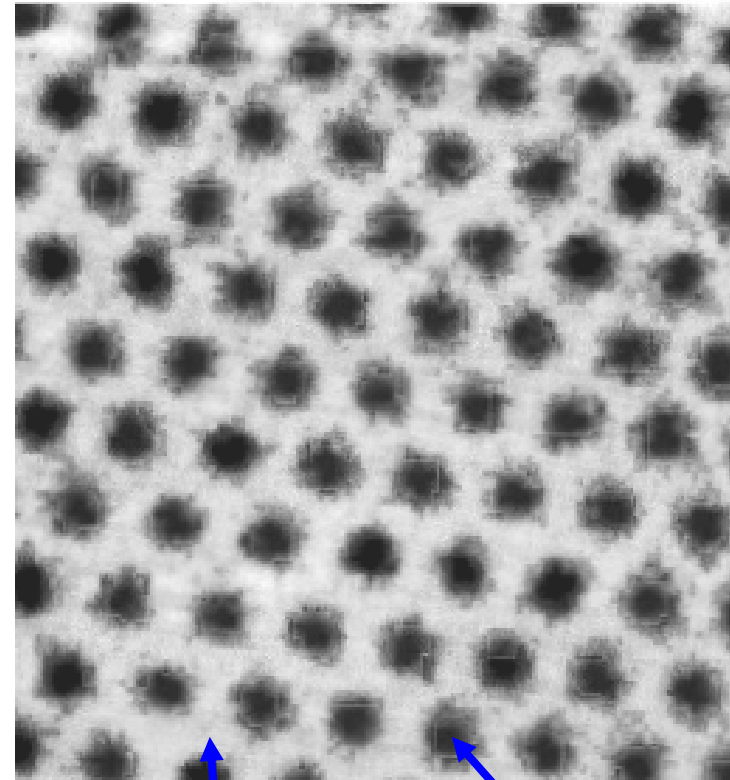
Negative bias applied,  
electrons tunnel from the  
sample



# STM imaging vortices in a superconductor



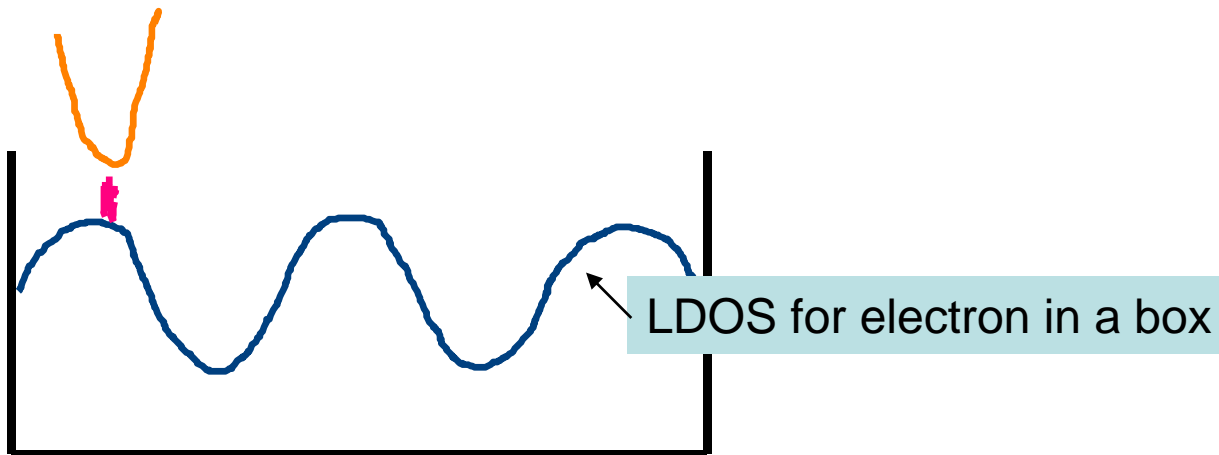
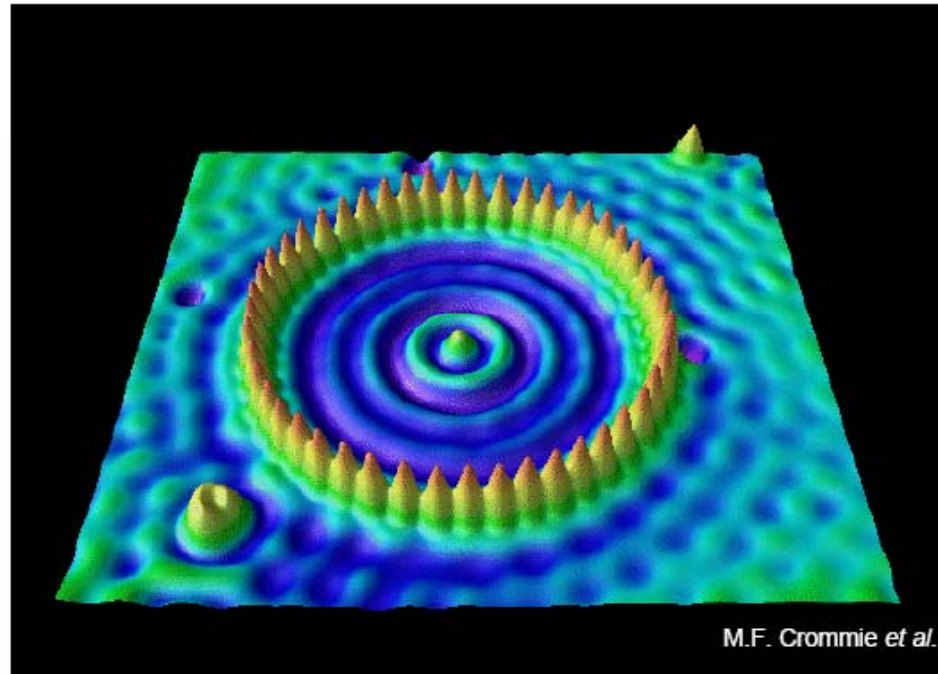
Imaging set point



Superconductor  
(bright, high LDOS  
at set point)

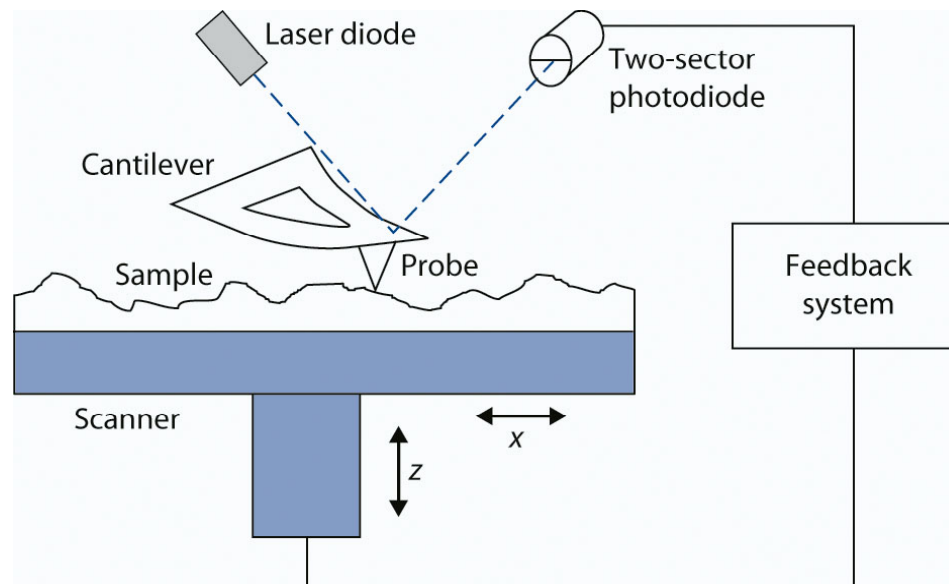
Vortex (normal  
core), dark - low  
LDOS at set  
point)

# Electron in a box



# Scanning probe techniques

- AFM and related techniques:
  - Lateral force microscopy (LFM)
  - Magnetic force microscopy (MFM)
  - Electrostatic force microscopy (EFM) etc...



# Problems (end of chapter)

- 8.1
- 8.2. What parameters can be used to change the force between tip and surface when operating in liquid?